



# Product Change Notification

## 112334 - 00

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# Product Change Notification

**Change Notification #:** 112334 - 00

**Change Title:** Next Unit of Computing Kit DC3217IYE Boxed and Bulk  
PCN 112334-00, Product Design, Documentation Change Bottom Cover and Update Integration Guide

**Date of Publication:** June 4, 2013

## Key Characteristics of the Change:

Product Design  
Documentation

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jun 21, 2013
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## Description of Change to the Customer:

Intel will be upgrading the bottom cover to include a 3.5mm thermal pad to enhance the thermal design. See images below.

Also, the integration guide for BLKDC3217IYE will be updated.

Current Bottom Cover:



New Bottom Cover:



**Customer Impact of Change and Recommended Action:**

This change has been thoroughly evaluated to ensure there is no quality, reliability or functional implication to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

**Products Affected / Intel Ordering Codes:**

Product Code	MM#	Pre Change TA	Pre Change SA	Post Change TA	Post Change SA
BOXDC3217IYE	924222	N/A	G80097-103	N/A	G80097-104
BLKDC3217IYE	930690	G99503-102	G99512-103	G99503-103	G99512-104

**PCN Revision History:****Date of Revision:**

June 4, 2013

**Revision Number:**

00

**Reason:**

Originally Published PCN